ISO9001:2000 Certified SCI Quality System

Sierra Components, Inc.

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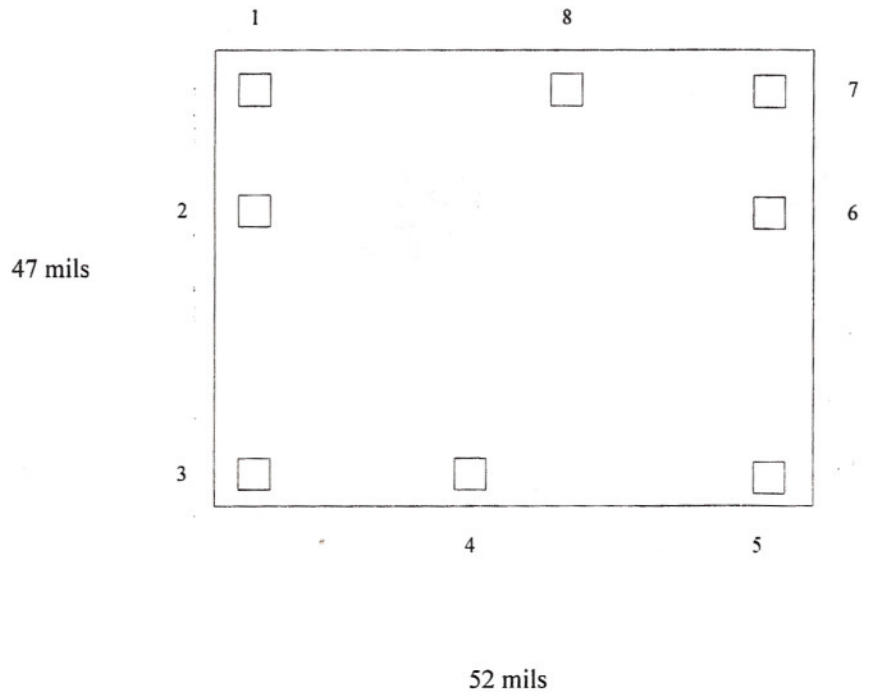
Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD FUNCTIONS

1	A
2	B
3	C = N A.B
4	VSS
5	F = N D.E
6	E
7	D
8	VDD

Top Material: Al
Backside Material: Si
Bond Pad Size: .004"X.004"
Backside Potential: VDD
Mask Ref:

APPROVED BY: JK	**DIE SIZE : .047"x .052"**	**DATE: 4/30/07**
MFG: TIH	**THICKNESS:**	**P/N: CD40107B**